



Product Change Notification: DSNO-27BDNH748

Date:

29-Jul-2026

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 8402 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected AT89C51AC2, AT89C51AC3, AT89C51CC01, AT89C51CC03, AT89C51ED2, AT89C51IC2, AT89C51ID2, AT89C51RB2, AT89C51RC2, AT89C51RD2 and AT89CC01UAEDS device families available in 44L TQFP (10x10x1mm) package at MTAI assembly site.

Affected CPNs:

[DSNO-27BDNH748_Affected_CPN_07292026.pdf](#)

[DSNO-27BDNH748_Affected_CPN_07292026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected AT89C51AC2, AT89C51AC3, AT89C51CC01, AT89C51CC03, AT89C51ED2, AT89C51IC2, AT89C51ID2, AT89C51RB2, AT89C51RC2, AT89C51RD2 and AT89CC01UAEDS device families available in 44L TQFP (10x10x1mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology	Microchip Technology	No

	Thailand (HQ) (MTAI)	Thailand (HQ) (MTAI)	
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700HA	G700HA	No
Lead-Frame Material	C7025	C7025	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 26 October 2026 (date code: 2644)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	October 2026				
Work Week	27	28	29	30	31		40	41	42	43	44
Qual Report Availability					x						
Final PCN Issue Date					x						
Estimated Implementation Date											x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB# 16-1206, 7627 and 7042.

Revision History: July 29, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-27BDNH748_Qual Report_CCB.7042.pdf](#)

[PCN_DSNO-27BDNH748_Qual Report_CCB16-1206 and 7627.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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